

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-16 (Canceled).

Claim 17 (Currently Amended): A vacuum processing apparatus for generating a plasma ~~including~~ comprises a vacuum processing chamber having a stage for mounting a substrate to be subjected to a plasma processing ~~processed~~, and a carrier port for providing access to and from ~~carrying the substrate onto and off the stage for subjecting the substrate on the stage to a plasma processing in the vacuum processing chamber~~, said apparatus, comprising:

a deposit shield disposed along an inner peripheral wall of the vacuum processing chamber, said deposit shield ~~and~~ having a notch portion at a position facing the carrier port;

a shutter being shaped to fit ~~having a shape fitted~~ into the notch portion of the deposit shield and being configured to be elevated, wherein, when the shutter is fitted inside the notch portion of the deposit shield, having an inside surface of the shutter is substantially flush with an inside surface of the deposit shield ~~a same inside curvature as an even curvature of an inner surface of the deposit shield when the shutter is fitted into the notch portion, and being configured to be elevated;~~

a sealing groove being configured to receive an O-ring therein, said sealing groove being formed in an end face of the shutter opposing a flat side face of the deposit shield; and

a ~~conduction~~ groove being configured to receive therein a spiral seal made of metal, said ~~conduction~~ groove formed in the end face of the shutter parallel to and outside of the sealing groove, the spiral seal electrically connecting the deposit shield to the shutter,

wherein each of the deposit shield and the shutter is configured to have a ground potential, the shutter is configured to be retreated from the notch portion when moving the

substrate in and out of the stage through the carrier port and configured to be fitted into the notch portion of the deposit shield when the plasma processing is conducted, thus surrounding a plasma generation region by ~~the~~ an even curvature of the shutter and deposit shield thereby producing a uniform plasma.

Claim 18 (Currently Amended): A vacuum processing apparatus for generating a plasma ~~including~~ comprises a vacuum processing chamber having a stage for mounting a substrate to be subjected to a plasma processing ~~processed~~, and a carrier port for providing access to and from ~~carrying the substrate onto and off the stage for subjecting the substrate on the stage to a plasma processing in the vacuum processing chamber~~, said apparatus, comprising:

a deposit shield disposed along an inner peripheral wall of the vacuum processing chamber, said deposit shield ~~and~~ having a notch portion at a position facing the carrier port;

a shutter being shaped to fit ~~having a shape fitted~~ into the notch portion of the deposit shield and being configured to be elevated, wherein, when the shutter is fitted inside the notch portion of the deposit shield, having an inside surface of the shutter is substantially flush with an inside surface of the deposit shield ~~a same inside curvature as an even curvature of an inner surface of the deposit shield when the shutter is fitted into the notch portion, and being configured to be elevated;~~

a shutter mechanism configured to raise the shutter into the notch portion of the deposit shield when the plasma is generated in the vacuum processing chamber, thereby closing the carrier port,

a sealing groove being configured to receive an O-ring therein, said sealing groove being formed in an end face of the shutter opposing a flat side face of the deposit shield; and

a ~~conduction~~ groove being configured to receive therein a spiral seal made of metal, said ~~conduction~~ groove formed in the end face of the shutter parallel to and outside of the sealing groove, the spiral seal electrically connecting the deposit shield to the shutter,

~~wherein when the plasma is generated in the vacuum processing chamber, the shutter is raised by a shutter mechanism to be fitted into the notch portion thereby closing the carrier port and forming the same inner surface curvature as the even curvature of the inner surface of the deposit shield, and~~

wherein ~~further~~ each of the deposit shield and the shutter is configured to have a ground potential, the shutter is configured to be retreated from the notch portion when moving the substrate in and out of the stage through the carrier port and configured to be fitted into the notch portion of the deposit shield when the plasma processing is conducted, thus surrounding a plasma generation region by the even curvature of the shutter and deposit shield thereby producing a uniform plasma.

Claim 19 (Currently Amended): A vacuum processing apparatus for generating a plasma ~~including~~ comprises a vacuum processing chamber having a stage for mounting a substrate to be subjected to a plasma processing ~~processed~~, and a carrier port for providing access to and from ~~carrying the substrate onto and off the stage for subjecting the substrate on the stage to a plasma processing in the vacuum processing chamber~~, said apparatus, comprising:

a deposit shield disposed along an inner peripheral wall of the vacuum processing chamber, said deposit shield ~~and~~ having a notch portion at a position facing the carrier port;

a shutter being shaped to fit ~~having a shape fitted~~ into the notch portion of the deposit shield and being configured to be elevated, wherein, when the shutter is fitted inside the notch portion of the deposit shield, having an inside surface of the shutter is substantially

flush with an inside surface of the deposit shield ~~a same inside curvature as an even curvature of an inner surface of the deposit shield when the shutter is fitted into the notch portion, and being configured to be elevated;~~

a sealing groove being configured to receive an O-ring therein, said sealing groove being formed in an end face of the shutter opposing a flat side face of the deposit shield; and

a ~~conduction~~ groove being configured to receive therein a spiral seal made of metal, said ~~conduction~~ groove formed in the end face of the shutter parallel to and outside of the sealing groove, the spiral seal electrically connecting the deposit shield to the shutter.

Claim 20 (Previously Presented): The vacuum processing apparatus according to claim 19, wherein a disk-shaped evacuation plate is disposed around the stage, and the shutter and the evacuation plate are brought into contact with each other and electrically connected to each other when the shutter is raised.

Claim 21 (Previously Presented): The vacuum processing apparatus according to Claim 19, wherein each of the deposit shield and the shutter comprises a heating mechanism.

Claim 22 (Currently Amended): A vacuum processing apparatus for generating a plasma ~~including~~ comprises a vacuum processing chamber having a stage for mounting a substrate to be subjected to a plasma processing ~~processed~~, and a carrier port provided on a peripheral wall of the vacuum processing chamber for providing access to and from ~~carrying the substrate onto and off the stage for subjecting the substrate on the stage to a plasma processing in the vacuum processing chamber~~, said apparatus, comprising:

a deposit shield disposed along an inner peripheral wall of the vacuum processing chamber, said deposit shield ~~and~~ having a notch portion at a position facing the carrier port,

the notch having an end face having an L-shape cross section, the end face of the L-shape cross section having a convex outer periphery;

a shutter being shaped to fit ~~having a shape fitted~~ into the notch portion of the deposit shield and being configured to be elevated, wherein, when the shutter is fitted inside the notch portion of the deposit shield, having an inside surface of the shutter is substantially flush with an inside surface of the deposit shield ~~a same inside curvature as an even curvature of an inner surface of the deposit shield when the shutter is fitted into the notch portion, and being configured to be elevated~~;

a sealing groove being configured to receive an O-ring therein, said sealing groove being formed in an end face of the shutter opposing a flat side face of the deposit shield; and

a ~~conduction~~ groove being configured to receive therein a spiral seal made of metal, said ~~conduction~~ groove formed in the end face of the shutter parallel to and outside of the sealing groove, the spiral seal electrically connecting the deposit shield to the shutter.

Claim 23 (Previously Presented): The vacuum processing apparatus according to claim 22, wherein a disk-shaped evacuation plate is disposed around the stage, and the shutter and the evacuation plate are brought into contact with each other and electrically connected to each other when the shutter is raised.

Claim 24 (Previously Presented): The vacuum processing apparatus according to claim 22, wherein each of the deposit shield and the shutter comprises a heating mechanism.

Claim 25 (Currently Amended): A vacuum processing apparatus for generating a plasma ~~including~~, comprises a vacuum processing chamber having a stage for mounting a substrate to be subjected to a plasma processing ~~processed~~, and a carrier port provided on a

peripheral wall of the vacuum processing chamber for providing access to and from ~~carrying~~
~~the substrate onto and off the stage for subjecting the substrate on the stage to a plasma~~
~~processing in the vacuum processing chamber~~, said apparatus, comprising:

a deposit shield disposed along an inner peripheral wall of the vacuum processing chamber, said deposit shield having a first heating mechanism; and

a shutter configured to be elevated along the inner peripheral wall of the vacuum processing chamber, said shutter having a second heating mechanism,

wherein each of the deposit shield and the shutter is configured to have a grounded potential, the shutter is configured to be retreated when the substrate is moved in and out of the stage through the carrier port and configured to be abutted on the deposit shield when the plasma processing is conducted, thus surrounding a plasma generation region by a substantially flush curvature formed by an inside surface of the shutter and an inside surface of the deposit shield ~~an even curvature of the shutter and deposit shield~~ thereby generating a uniform plasma.

Claim 26 (Previously Presented): The vacuum processing apparatus according to claim 25, wherein a disk-shaped evacuation plate is disposed around the stage, and the shutter and the evacuation plate are brought into contact with each other and electrically connected to each other when the shutter is raised.